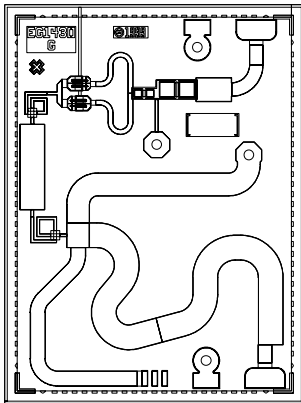


**20 - 40 GHz X3 Frequency Multiplier**

**TGC1430G**



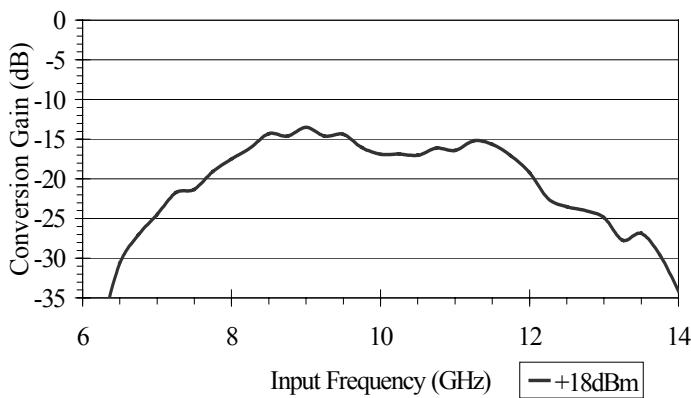
Chip Dimensions 1.50 mm x 2.0 mm

**Key Features and Performance**

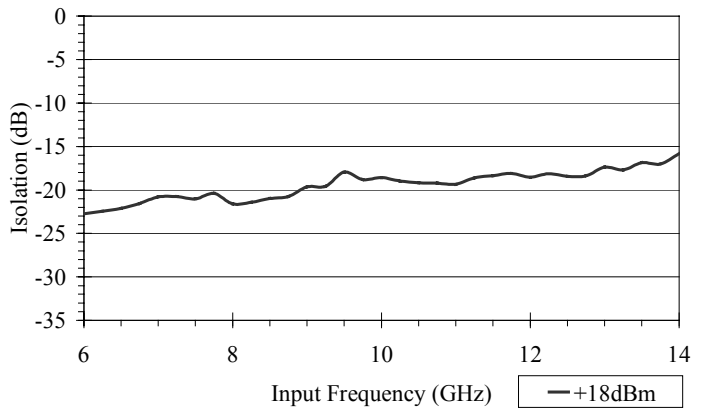
- 0.25um pHEMT Technology
- 20 - 40 GHz Output Frequencies
- 8.5 - 13.5 GHz Fundamental Frequencies
- -15 +/- 2dB Conversion Gain
- 18 dBm Input Drive Optimum
- 15dB Fundamental Isolation
- 30dB 2nd Harmonic Isolation

**Primary Applications**

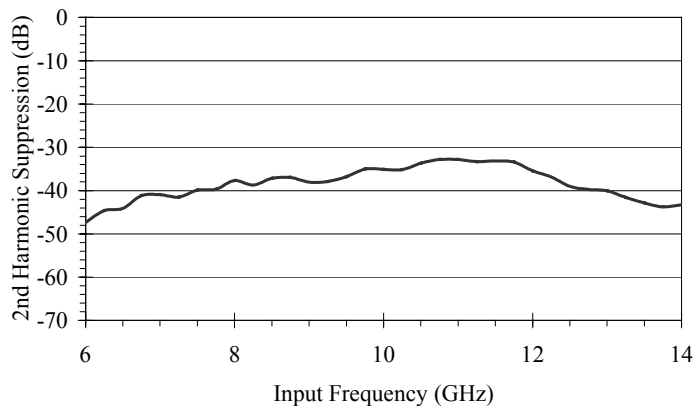
- Point-to-Point Radio
- Point-to-Multipoint Communications



Conversion Gain vs Input Frequency (Input @ 18dBm)

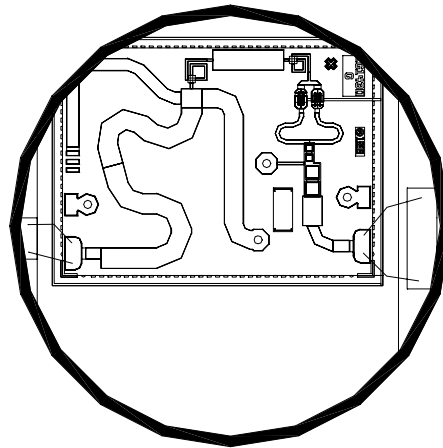
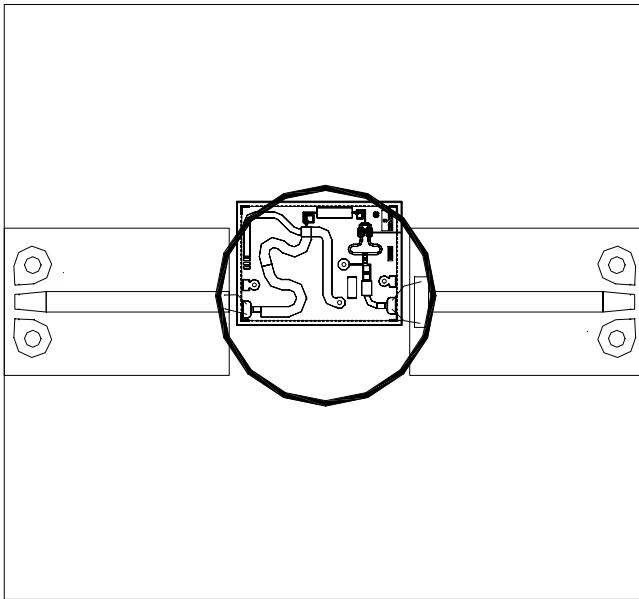


Fundamental Isolation



2nd Harmonic Suppression

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications subject to change without notice



TGC1430G - Recommended Assembly Drawing

*Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications subject to change without notice*



## Assembly Process Notes

Reflow process assembly notes:

- AuSn (80/20) solder with limited exposure to temperatures at or above 300°C
- alloy station or conveyor furnace with reducing atmosphere
- no fluxes should be utilized
- coefficient of thermal expansion matching is critical for long-term reliability
- storage in dry nitrogen atmosphere

Component placement and adhesive attachment assembly notes:

- vacuum pencils and/or vacuum collets preferred method of pick up
- avoidance of air bridges during placement
- force impact critical during auto placement
- organic attachment can be used in low-power applications
- curing should be done in a convection oven; proper exhaust is a safety concern
- microwave or radiant curing should not be used because of differential heating
- coefficient of thermal expansion matching is critical

Interconnect process assembly notes:

- thermosonic ball bonding is the preferred interconnect technique
- force, time, and ultrasonics are critical parameters
- aluminum wire should not be used
- discrete FET devices with small pad sizes should be bonded with 0.0007-inch wire
- maximum stage temperature: 200°C

***GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.***

*Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.*

